

WP917CK/4EGWT

2 x 3 mm Quad-Level Circuit Board Indicator

DESCRIPTIONS

- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode
- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode

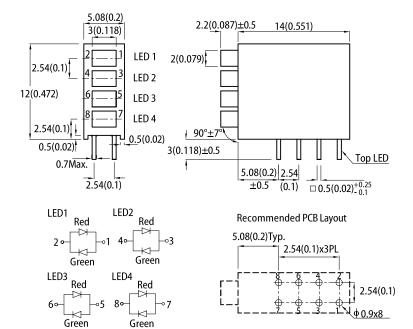
FEATURES

- · Quad-level design, save board space
- · Different color combination available
- · Black case enhances contrast
- Housing UL rating: 94V-0
- Housing material: Type 66 nylon
- RoHS compliant

APPLICATIONS

- · Status indicator
- Illuminator
- Signage applications
- · Decorative and entertainment lighting
- · Commercial and residential architectural lighting

PACKAGE DIMENSIONS



- All dimensions are in millimeters (inches)

- 1. Air unimisation are in minimited in finite and in the state of the

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
WP917CK/4EGWT	High Efficiency Red (GaAsP/GaP)	White Diffused	5	10		
			*2	*6	140°	
	Green (GaP)		5	10		
			*5	*10		

Notes.

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

* Luminous intensity value is traceable to CIE127-2007 standards.



ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Farameter		Emitting Color	Тур.	Max.	Oilit
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	High Efficiency Red Green	627 565	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	High Efficiency Red Green	617 568	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	High Efficiency Red Green	45 30	-	nm
Capacitance	С	High Efficiency Red Green	15 15	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	High Efficiency Red Green	2.0 2.2	2.5 2.5	V

Notes:

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

P		Valu			
Parameter	Symbol	High Efficiency Red	Green	Unit	
Power Dissipation	P _D	75 62.5		mW	
Junction Temperature	T _j	125 110		°C	
Operating Temperature	T _{op}	-40 to +85		°C	
Storage Temperature	T _{stg}	-40 to +85		°C	
DC Forward Current	I _F	30	25	mA	
Peak Forward Current	I _{FM} ^[1]	160	140	mA	
Electrostatic Discharge Threshold (HBM)	-	8000	8000	V	
Lead Solder Temperature [2]		260°C For 3 Seconds			
Lead Solder Temperature [3]		260°C For 5 Seconds			

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.
4. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity — Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



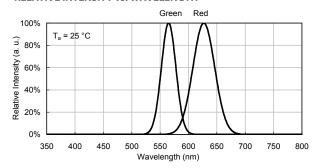
^{1.} The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance $\lambda d:\pm 1$ nm.)

^{2.} Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

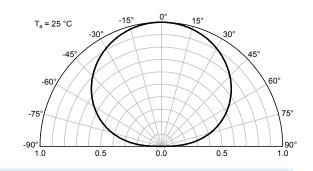


TECHNICAL DATA

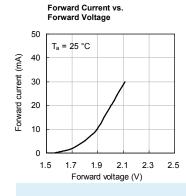
RELATIVE INTENSITY vs. WAVELENGTH

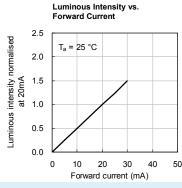


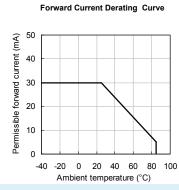
SPATIAL DISTRIBUTION

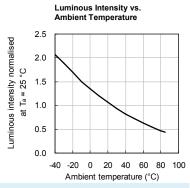


HIGH EFFICIENCY RED

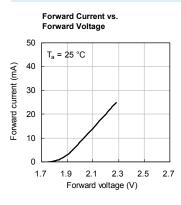


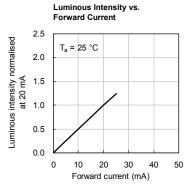


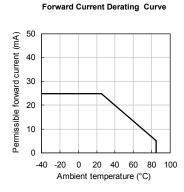


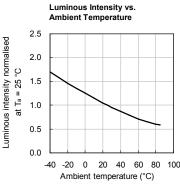


GREEN

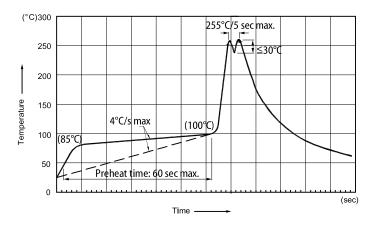








RECOMMENDED WAVE SOLDERING PROFILE



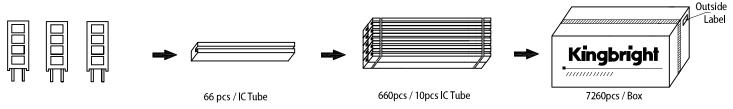
- 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
 Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.

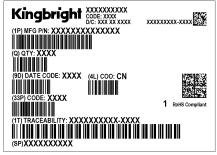
 5. SAC 305 solder alloy is recommended.

 6. No more than one wave soldering pass.



PACKING & LABEL SPECIFICATIONS





PRECAUTIONS

Storage Conditions

- 1. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- 2. LEDs should be stored with temperature ≤ 30°C and relative humidity < 60%.
- 3. Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.

LED Mounting Method

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

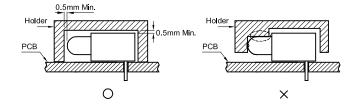
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

Housing Housing Housing Housing 1 Note.3 45° Max O O 0 Housing Housing Housing LED Housing LED

O" Correct mounting method " x " Incorrect mounting method

Lead Forming Procedures

- 1. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.
- 2. The tip of the soldering iron should never touch the lens epoxy.
- 3. Through-hole LEDs are incompatible with reflow soldering.
- 4. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

 The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
- liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance
- The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- All design applications should refer to Kingbright application notes available at https://w



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Kingbright:

WP917CK/4EGWT WP917CK/4EGW